

ECCM9NA10-13.824M TR



ITEM DESCRIPTION

Quartz Crystal Resonator 3.2mm x 5.0mm x 1.0mm 4 Pad Ceramic Surface Mount (SMD) 13.824MHz ± 10 ppm at 25°C, ± 15 ppm over 0°C to +70°C 10pF Parallel Resonant

ELECTRICAL SPECIFICATIONS

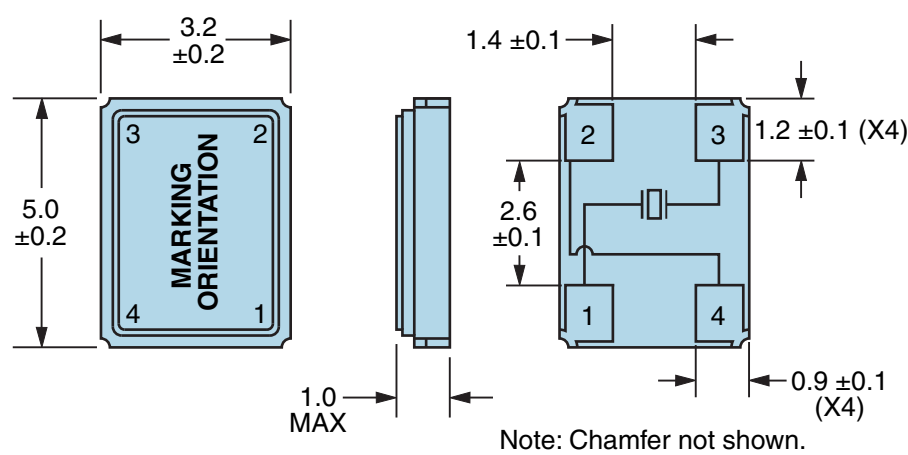
Nominal Frequency	13.824MHz
Frequency Tolerance/Stability	± 10 ppm at 25°C, ± 15 ppm over 0°C to +70°C
Aging at 25°C	± 3 ppm/Year Maximum
Load Capacitance	10pF Parallel Resonant
Shunt Capacitance	7pF Maximum
Equivalent Series Resistance	55 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	100 μ Watts Maximum
Spurious Response	-3dB Minimum (Measured from Fo to Fo+5000ppm)
Storage Temperature Range	-40°C to +125°C
Insulation Resistance	500 Megaohms Minimum (Measured at 100Vdc)

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

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MECHANICAL DIMENSIONS (all dimensions in millimeters)

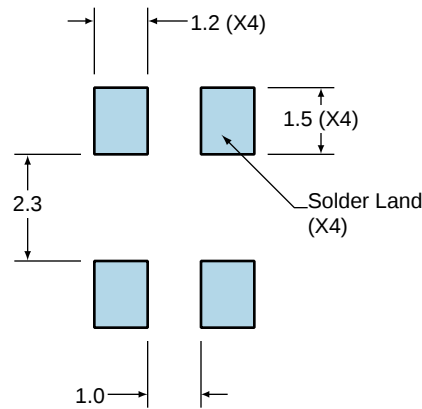


PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

LINE	MARKING
1	E13.82 <i>E=Ecliptek Designator</i>
2	XXXXX <i>XXXXX=Ecliptek Manufacturing Identifier</i>

Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

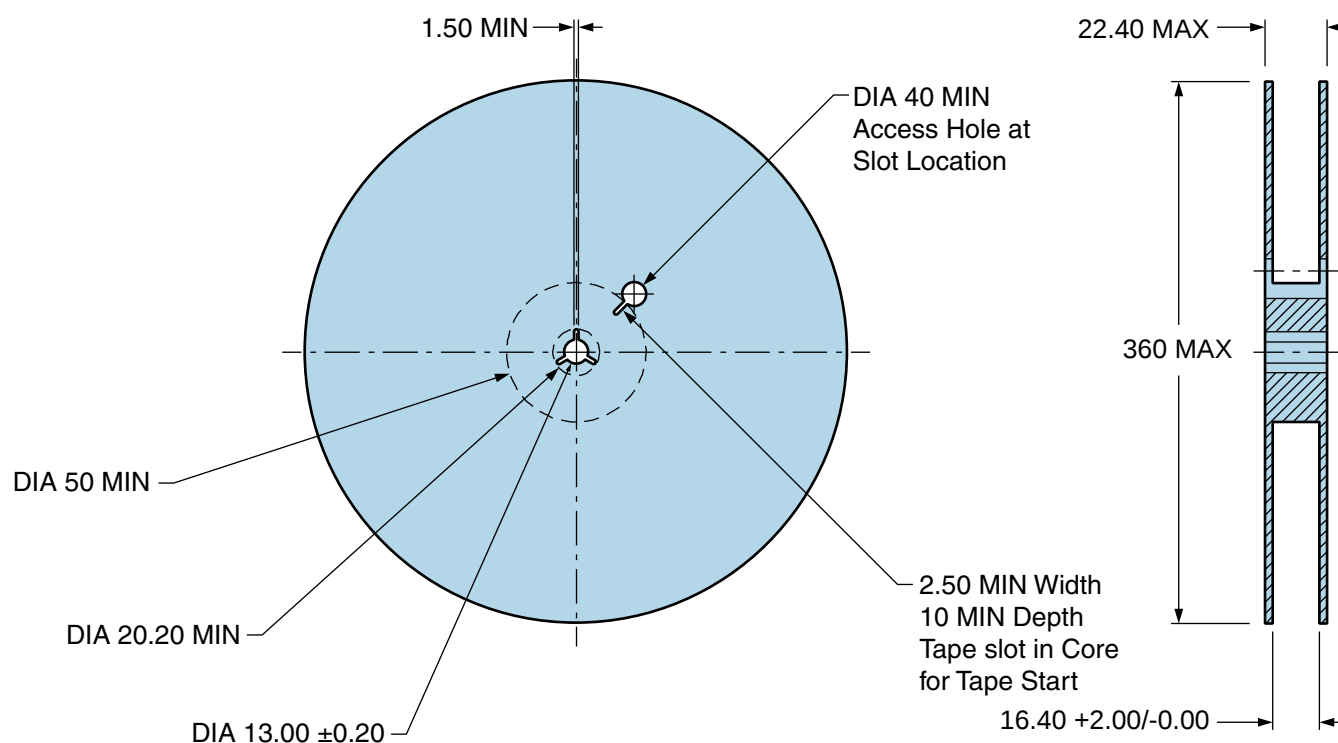
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Tape & Reel Dimensions

Quantity Per Reel: 1,000 units

All Dimensions in Millimeters

Compliant to EIA-481



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Recommended Solder Reflow Methods



High Temperature Infrared/Convection

Ts MAX to TL (Ramp-up Rate)	3°C/Second Maximum
Preheat	
- Temperature Minimum (Ts MIN)	150°C
- Temperature Typical (Ts TYP)	175°C
- Temperature Maximum (Ts MAX)	200°C
- Time (ts MIN)	60 - 180 Seconds
Ramp-up Rate (TL to TP)	3°C/Second Maximum
Time Maintained Above:	
- Temperature (TL)	217°C
- Time (tL)	60 - 150 Seconds
Peak Temperature (TP)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature (TP Target)	250°C +0/-5°C
Time within 5°C of actual peak (tp)	20 - 40 Seconds
Ramp-down Rate	6°C/Second Maximum
Time 25°C to Peak Temperature (t)	8 Minutes Maximum
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 245°C

Ts MAX to TL (Ramp-up Rate)		5°C/Second Maximum
Preheat		
- Temperature Minimum (Ts MIN)	N/A	
- Temperature Typical (Ts TYP)	150°C	
- Temperature Maximum (Ts MAX)	N/A	
- Time (ts MIN)	30 - 60 Seconds	
Ramp-up Rate (TL to TP)		5°C/Second Maximum
Time Maintained Above:		
- Temperature (TL)	150°C	
- Time (tL)	200 Seconds Maximum	
Peak Temperature (TP)		245°C Maximum
Target Peak Temperature (TP Target)		245°C Maximum 2 Times / 230°C Maximum 1 Time
Time within 5°C of actual peak (tp)		10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate		5°C/Second Maximum
Time 25°C to Peak Temperature (t)		N/A
Moisture Sensitivity Level		Level 1
Additional Notes		Temperatures shown are applied to body of device.

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)